

Moible-ITX Board

Credit Card-Size Efficiency INDUSTRIAL-GRADE PERFORMANCE



Features

- Ultra-Compact size with Mobile-ITX , 60x60mm size for space-saving applications
- Powered by Dual-core ARM Cortex-A7 with 128MB DDR3
- 8GB eMMC storage on board design
- Single-core HiFi4 DSP for high-efficiency processing
- H.265/H.264 decoding with GPU acceleration for smooth 1080p video
- Multimedia Interfaces: MIPI-DSI (1920x1200), I2C touch, 1x headphone/Line-out and 1x MIC-in for rich audio and display integration
- Flexible Expansion: 4x USB 2.0 HS, USB Type-C for debugging, and 3x UART with flow control, offering broad connectivity options for various peripherals

LINE Pay

 Linux OS with LVGL, Qt, GTK+ support for fast GUI development



Introduction

MBM-T113 is powered by Allwinner T113-S3 processor. delivers exceptional versatility with dual-core ARM Cortex-A7, HiFi4 DSP, and 4GB eMMC storage. Its MIPI-DSI, I2C touch interface, and GPIO make it ideal for automotive dashboards and industrial control panels. USB and UARTs support seamless connectivity for IoT devices and medical equipment. With Line-out and MIC-in, it enables audio-driven smart gateways and multimedia systems. Optimized for Linux OS with GUI libraries like LVGL and Qt, the MBM-T113 is perfect for HMI applications in smart homes, industrial automation, and healthcare solutions.Small in size, big in possibilities.

Specification				
	Processor	Dual-core ARM Cortex-A7 @ 1.2GHz		
	RAM	On-chip Memory, 128MB DDR3		
System	Storage	8GB eMMC flash onboard and 1x Micro SD slot		
	Display	MIPI DSI w/1080p60		
	Touch	Support via I2C		
	Ethernet	10/100Mbps		
	Ethernet	1x RJ45 w/ LED indicator		
	USB Port	2x USB 2.0 Type A (USB 1/2), 2x USB 2.0 via 1x 4P Header 1x Type C for Debug/FW update		
I/O Interface	UART	3x UART with flow control (UART 1/2, 1x4P Header; UART3, 1x6P Header)		
	GPIO	1x GPIO for external extention		
	Audio	1x Headphone/Line-out;1x MIC-in		



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sales@fusiontech.com.tw

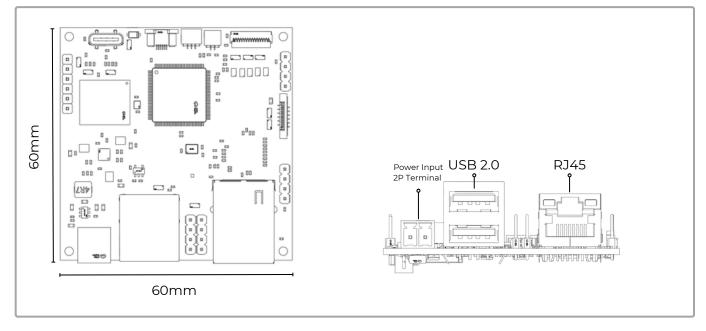
All specifications and photos are subject to change without notice



MBM-T113

Mobile-ITX Board

Dimension(mm)



Specification		
Power Input	5~12V via 1x 2P Terminal Block Phoenix Contact	
Form Factor 60x 60mm, Mobile-ITX		
Operating Temperature	-10°C ~ 70°C	
Operating System	Linux with LVGL, Qt, GTK+ support	



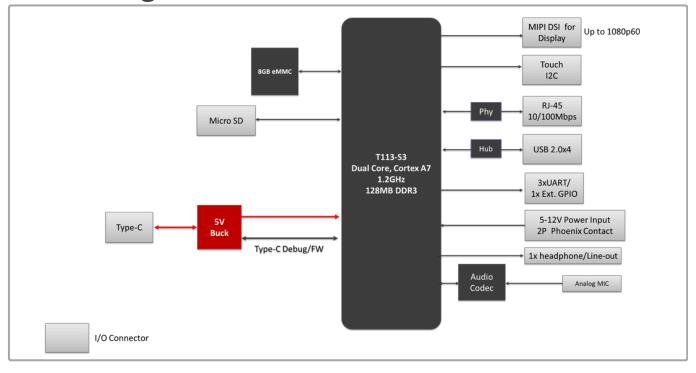




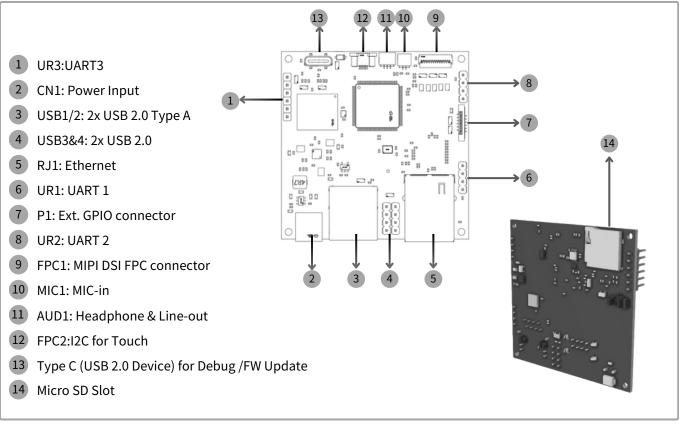
Mobile-ITX Board

Block Diagram

MBM-T113



I/O Briefing



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UR3: UART3 1

1x6-Pin Header, 2.54mm

	PIN	Assignment
	1	5V_SYS
	2	UART1_RX
۲ سا	3	UART1_TX
	4	UART1_CTS
	5	UART1_RTS
	6	GND

UR1: UART 1 6 1x4-Pin Header, 2.54mm

PIN	Assignment
1	3.3V
2	RX3
3	TX3
4	GND
	1 2



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P1: Ext. GPIO connector 1x12-Pin Ext. GPIO connector, P:0.5mm

	PIN	Assignment	PIN	Assignment
	1	12V	2	12V
1	3	GPADC0	4	PD13
	5	PD12	6	PD14
12	7	PD15	8	PD16
	9	PD11	10	PD10
	11	GND	12	GND



UR2: UART 2 1x4-Pin Header 2.54mm

 PIN	Assignment
1	3.3V
2	I2C1-SCK_RX5
3	I2C1-SDA_TX5
4	GND

USB3/4: 2x USB 2.0 1x4-Pin Header, 2.54mm

CN1: 5~12V Power Input

+

PIN

1

2

Assignment

12V

GND

Assignment

VBUS_34

USB_HUB_P3_D-

USB_HUB_P3_D+

GND

2

4



USB3

PIN

1

2

3

4

USB4

PIN	Assignment
1	VBUS_34
2	USB_HUB_P4_D-
3	USB_HUB_P4_D+
4	GND

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Drive into your future

MBM-T113

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FPC1: MIPI DSI, FPC Connector 1x 31-Pin FPC Connector, P=0.3mm (FH35C-31S-0.3SHW(50)

PIN	Assignment	PIN	Assignment
1	LED_A	2	LED_A
3	LED_A	4	N/A
5	LED_K	6	LED_K
7	LED_K	8	LED_K
9	GND	10	GND
11	MIPI_TXJ_D2+	12	MIPI_TXJ_D2_
13	GND	14	MIPI_TXJ_D1+
15	MIPI_TXJ_D1-	16	GND
17	MIPI_TXJ_CLK+	18	MIPI_TXJ_CLK-
19	GND	20	MIPI_TXJ_D0+
21	MIPI_TXJ_D0-	22	GND
23	MIPI_TXJ_D3+	24	MIPI_TXJ_D3-
25	GND	26	VDD_1P8
27	PG13_LCD_RST	28	GND
29	VDD_1P8	30	3V3
31	3V3		

12 FPC2: I2C for Touch 1x6-Pin FFC Connector, 0.5mm

	PIN	Assignment
	1	GND
	2	PG14_TP_INT
	3	PG15_TP_RST
	4	3V3
	5	PC2_I2C0_SDA
	6	PB3_I2C0_SCK

10 MIC: MIC-In 1x2-Pin wafer, 1mm

PIN	Assignment
1	MICIN+
2	MICIN-

11 AUD1: Headphone & Line-out 1x3-Pin wafer, 1mm

	PIN	Assignment
	1	HPOUTL
	2	HPOUTR
	3	GND

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